ResinFormulators
INNOVATIVE MATTERS

RF 2869 MOD 2 1-COMPONENT SYSTEM

RF 2869 Mod 2 is a one-part, silver filled, electrically conductive epoxy adhesive. This system does not require mixing or vacuum degassing. Cure is achieved at temperatures as low as 82°C (180°F) for one hour or a short dwell at 121°C (250°F) for three minutes. Because RF 2869 Mod 2 is already vacuum degassed during manufacturing and no mixing is required, a void free casting or bond line is easily achieved. When cured, this adhesive will have very high thermal and electrically conductive properties.

HANDLING PROPERTIES, TYPICAL

PROPERTY	RF 2869
Mixed Color	Silver
Mixed Viscosity @ 77°F (25°C)	300,000 (Thixotropic)
Out Time @ 77°F (25°C)	3 days
Gel Time, 10 grams @ 180°F (82°C) 250°F (121°C)	10 min 3 min
Cure Schedule	1 hr @ 82°C or 15 min @ 121°C

USES & APPLICATIONS

RF 2869 Mod 2 is suitable for electrical circuit connections, grounding of composites or hardware, static dissipation, and RFI shielding.

PHYSICAL PROPERTIES, TYPICAL CURED PERFORMANCE

PROPERTY	TEST METHOD	UNIT	VALUE
Volume Resistivity	ASTM B193	Ohm-cm	2.0E-04
Tensile Strength	ASTM D638	psi	8,300
Cured Hardness		Shore D	80+
DSC Tg	ASTM E1356	°C	68
CTE (below Tg)	ASTM E831	ppm/°C	50
CTE (above Tg)		ppm/°C	168

SPECIALTY PACKAGING AND DISPENSING

Material is suitable for syringe or cartridge packaging, as a one-component material.

LEARN MORE: Download the TDS or SDS from our TDS SDS Library »

POPULAR FOR USE IN:

ELECTRONICS

ELECTRIC VEHICLE

AEROSPACE

COMMITMENT TO QUALITY AND SERVICE

GracoRoberts and Resin Formulators are fully qualified to design, manufacture, and distribute products to a variety of industries.

Certifications:
- ISO9001:2015
- AS9100 (Rev. D)
- AS9120 (Rev. B)

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